



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**PATENT**

# 4 2/23/12  
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**In re Application of:**

Cobbley et al.

**Serial No.:** 09/639,486

**Filed:** August 14, 2000

**For:** METHOD OF ATTACHING SOLDER  
BALLS TO BGA PACKAGE UTILIZING A  
TOOL TO PICK AND DIP THE SOLDER  
BALL IN FLUX

**Examiner:** Z. Pittman

**Group Art Unit:** 1725

**Attorney Docket No.:** 3636.1US (97-1349.1)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

January 30, 2002  
Date of Deposit

Signature of registered practitioner or other person having reasonable basis to expect mailing to occur on date of deposit shown pursuant to 37 C.F.R. § 1.8(a)(1)(ii)

Deidra Pfeil  
Typed/printed name of person whose signature is contained above

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
Washington, D.C. 20231

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 be considered by the Examiner and made of record. The listed document is from co-pending application Serial No. 09/167,763, filed October 7, 1998. A copy of the listed document is enclosed pursuant to 37 C.F.R. § 1.98(a).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as

defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

DOCUMENTS

U.S. Patent Documents

<u>U.S. Patent No.</u>	<u>Issue Date</u>	<u>Inventor</u>
6,254,923 B1	07/2001	Boyd et al.

Applicants offer to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed after the mailing date of the first Office Action on the merits. I hereby certify that no item of information contained in the Supplemental Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned after making reasonable inquiry, was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of the statement.

Respectfully submitted,



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Date: January 30, 2002

JRD/sls:djp

Enclosures: Form PTO-1449  
Copy of document cited